

Amendment to the Claims

Claims 1-61 (Cancelled)

62.(New) A semiconductor wafer holder for use in an electroplating system, said wafer holder comprising:

a first holding member having a semiconductor wafer support surface;

a second holding member having an opening, and an annular packing comprising a first end projection for contacting a perimeter edge of a semiconductor wafer and a second end projection for contacting the first holding member;

a plurality of conductive elements for contacting a conductive layer on the perimeter edge of the semiconductor wafer, the conductive elements being disposed between the first and second end projections of the packing, and being electrically connected to an external electrode; and

a ring clamp rotatable relative to the opening of the second holding member to clamp together the first holding member and the second holding member through the semiconductor wafer on the semiconductor wafer support surface and the packing.

63.(New) A semiconductor wafer holder according to claim 62, wherein the second holding member comprises a ring.

64.(New) A semiconductor wafer holder according to claim 62, further comprising a member for resiliently pressing the conductive elements against the conductive layer of the semiconductor wafer in a closed position of the holder.

65.(New) A semiconductor wafer holder according to claim 62, wherein the first holding member is plate-shaped.

66.(New) A semiconductor wafer holder according to claim 62, wherein the first holding member has a plurality of pawls, and the ring clamp has a plurality of protrusions adapted to slide below the pawls.

67.(New) A semiconductor wafer holder according to claim 62, further comprising a hinge mechanism by which said first holding member and said second holding member are connected.

68.(New) A semiconductor wafer holder according to claim 62, wherein the second holding member comprises synthetic resin or rubber, or plastics.

69.(New) A semiconductor wafer holder according to claim 63, wherein the ring has a ring retainer and the ring clamp has a guide slot.

70.(New) An electroplating system for electroplating a semiconductor wafer, said system comprising:

a loading/unloading station,

a wafer loading/unloading table,

a plating bath,

a cleaning bath,

a wafer transfer robot for transferring a wafer between the loading/unloading station and the wafer loading/unloading table, and

a holder transfer robot for transferring a wafer holder holding the wafer between the wafer loading/unloading table, the plating bath, and the cleaning bath, wherein the wafer holder comprises:

a first holding member having a semiconductor wafer support surface;

a second holding member having an opening, and an annular packing comprising a first end projection for contacting a perimeter edge of a semiconductor wafer and a second end projection for contacting the first holding member;

a plurality of conductive elements for contacting a conductive layer on the perimeter edge of the semiconductor wafer, the conductive elements being disposed between the first and second end projections of the packing, and being electrically connected to an external electrode; and

a ring clamp rotatable relative to the opening of the second holding member to clamp together the first holding member and the second holding member through the semiconductor wafer on the semiconductor wafer support surface and the packing.